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TITLE: 783 I/O, FC BGA, 29 X 29 PKG, 1 MM PITCH, WITH FULL FOOTED LID	DOCUMENT NO: 98ARE10641D	REV: D
	STANDARD: NON-JEDEC	
	SOT1605-1	17 DEC 2015



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.
7. PACKAGE CODE SUMMARY:
PBGA – 8423
CBGA – 5112

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